

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims:

1. (currently amended) A heat sink assembly within a potted housing, comprising:
a bracket mounted to an interior surface of said housing;
a heat-containing element fully enclosed within said housing; and,
a self-tapping screw threaded into said bracket, engaging said heat-containing element, and urging said element against said bracket, wherein said housing is filled with potting material, said bracket is arranged to act as a first heat sink for said heat-containing element, and said heat-containing element is maintained in a fixed position within said housing by said bracket prior to said filling with said potting material.
2. (currently amended) The heat sink assembly as recited in Claim 1 wherein said heat-containing element further comprises a second heat sink; and,
wherein said self-tapping screw is operatively arranged to urge said second heat sink against said bracket.
3. (currently amended) The heat sink assembly as recited in Claim 2 wherein said heat-containing element further comprises a printed circuit board (PCB) comprising said second heat sink.
4. (currently amended) The heat sink assembly as recited in Claim 3 wherein said PCB further comprises an integrated circuit (IC) comprising said second heat sink.
5. (original) The heat sink assembly as recited in Claim 4 wherein said housing further comprises a housing for a fuel pump and said PCB further comprises an oscillator circuit.
6. (original) The heat sink assembly as recited in Claim 1 wherein said bracket is brass.
7. (original) The heat sink assembly as recited in Claim 1 wherein said bracket is connected to said interior surface with a fastener selected from the group including rivets and threaded fasteners.

8. (currently amended) A heat sink assembly in a potted housing for a fuel pump, comprising:

a brass bracket connected to an interior wall of said housing;

a printed circuit board (PCB) with a first heat sink, said PCB fully enclosed within said housing; and,

a self-tapping screw threaded into said bracket, engaging said PCB, and urging said first heat sink against said bracket, wherein said housing is filled with potting material, said bracket is arranged to act as a second heat sink for said heat-containing element, and said heat-containing element is maintained in a fixed position within said housing by said bracket prior to said filling with said potting material.

9. (currently amended) The heat sink assembly as recited in Claim 8 wherein said PCB further comprises an integrated circuit (IC) comprising said first heat sink.

10. (currently amended) The heat sink assembly as recited in Claim 9 wherein said PCB further comprises an oscillator circuit comprising said first heat sink.

11. (original) The heat sink assembly as recited in Claim 8 wherein said bracket is connected to said interior surface with a fastener selected from the group including rivets and threaded fasteners.

12. (currently amended) A heat sink assembly in a potted housing for an integral fuel pump, comprising:

a brass bracket connected to an interior wall of said housing with a rivet;

a printed circuit board (PCB) with an oscillator circuit and a heat sink, said PCB fully enclosed within said housing; and,

a self-tapping screw threaded into said bracket, engaging said PCB, and urging said heat sink against said brass bracket, wherein said housing is filled with potting material, said bracket is arranged to act as a heat sink for said heat-containing element, and said heat-containing element is maintained in a fixed position within said housing by said bracket prior to said filling with said potting material.

13. (currently amended) A method for transferring heat within a potted housing, comprising the steps of:

fully enclosing a heat-containing element within said potted housing;
connecting a mounting bracket to an interior wall of said housing;
threading a self-tapping screw into said mounting bracket; and,
with said screw, engaging said heat-containing element and pressing said heat-containing element against said mounting bracket;
maintaining, with said bracket, said heat-containing element in a fixed position within said housing;
filling said housing with potting material; and,
sinking heat from said heat-containing element with said bracket.

14. (original) The method recited in Claim 13 wherein said heat-containing element further comprises a circuit element with a heat sink; and,
wherein said pressing further comprises pressing said heat sink against said mounting bracket.

15. (original) The method recited in Claim 14 wherein said circuit element further comprises a printed circuit board (PCB) comprising said heat sink.

16. (original) The method recited in Claim 15 wherein said PCB further comprises an integrated circuit (IC) comprising said heat sink.

17. (original) The method recited in Claim 16 wherein said housing further comprises a housing for a fuel pump and said PCB further comprises an oscillator circuit.

18. (original) The method recited in Claim 13 further comprising:
forming said mounting bracket from brass.

19. (original) The method recited in Claim 13 wherein said connection further comprising connecting said mounting bracket to said interior surface using a fastener selected from the group including rivets and threaded fasteners.

20. (currently amended) A method for transferring heat within a potted housing for an integral fuel pump, comprising the steps of:

fully enclosing, within said potted housing, an oscillator circuit with a heat sink;

threadingly connecting a brass bracket to an interior wall of said housing;
threading a self-tapping screw into said mounting bracket;
contacting, with said self-tapping screw, said oscillator circuit with a heat sink; and,
urging said heat sink against said mounting bracket with said self-tapping screw;
maintaining, with said bracket, said heat-containing element in a fixed position within
said housing;
filling said housing with potting material; and,
sinking heat from said heat sink with said bracket.